Product Change Notification

Change Notification #:	**117615 - 01**
Change Title:	**Select Intel® Core™ Processors,** **Intel® Xeon® Processors,** **Intel® Celeron® Processors, and** **Intel® Pentium® Processors,** **PCN 117615-01,** **Product Material,** **Visual Change to Lidded Products** **Reason for Revision: Corrected the list of affected products**
Date of Publication:	**July 9, 2020**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	June 27, 2020

Description of Change to the Customer:

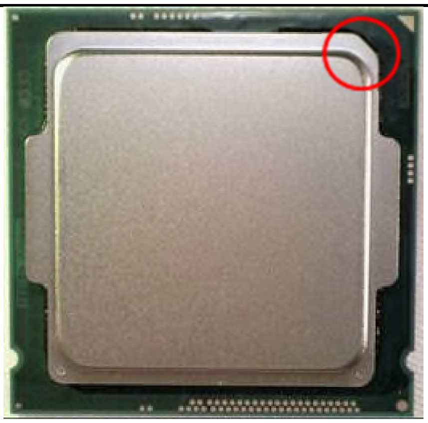
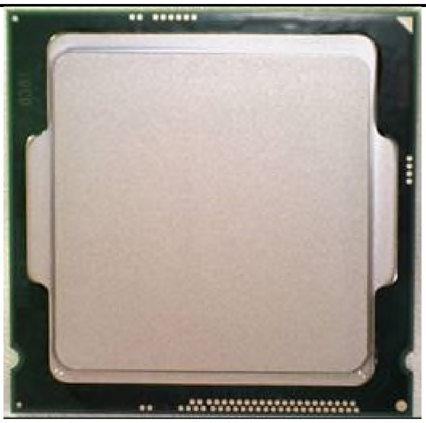
Reason for Revision: Corrected the list of affected products

Due to tooling end-of-life constraints and the lack of supplier support as well as process simplification, Intel will be changing the process used during Assembly to attach lids to substrate units resulting in a visual change to the lid. This process change will occur on all the Intel® Core™ Processors, Intel® Xeon® Processors, Intel® Celeron® Processors, Intel® Pentium® Processors and Boxed Intel® Xeon® Processors listed in the Products Affected / Intel Ordering Codes table below.

The lid process referred to as "old placement process" in the pictures below uses an older technology placed by a specific tool that will end of life. The process referred to below as the "new placement process" although similar, is the next generation. Both the old placement process and the new placement process attach lids to units, accomplishing the same function. However, moving to the new placement process results in a visual change to the product lid.

There is no change to the Form, Fit or Function of the product as a result of this change. This is strictly a result of using different toolsets to accomplish the same task. Customers do not need to do anything as a result of this change.

The new process mainly adds the chamfer in the new lid at upper right corner. See the scenario of mock up pictures below (for reference only).

LID	New placement process	Old placement process
Top view of units		
Number of dimples	2 dimples	2 dimples
Chamfer	Upper right of the corner	N/A

Customer Impact of Change and Recommended Action:

Customers do not need to do anything different due to this change. There is no change to the Form, Fit or Function of the product as a result of this change. This is strictly a result of using different toolsets to accomplish the same task.

For any questions or concerns, please contact your local Intel representative.

Products Affected / Intel Ordering Codes:

Marketing Name	Processor#	Stepping	Vertical Segment	Product Code	S-Spec	MM#
Intel® Core™ i7-4770S Processor	I7-4770S	C0	DESKTOP	CM8064601465504	S R14H	927944
Intel® Core™ i5-4570S Processor	I5-4570S	C0	DESKTOP	CM8064601465605	S R14J	927951
Intel® Xeon® Processor E3-1275 v3	E3-1275V3	C0	WORKSTATION	CM8064601466508	S R14S	927970
Intel® Xeon® Processor E3-1268L v3	E3-1268LV3	C0	EMBEDDED	CM8064601484200	S R17Y	929225
Intel® Core™ i5-4570TE Processor	I5-4570TE	C0	EMBEDDED	CM8064601484301	S R17Z	929226
Intel® Core™ i3-4330TE Processor	I3-4330TE	C0	EMBEDDED	CM8064601484402	S R180	929227
Intel® Pentium® Processor G3320TE	G3320TE	C0	EMBEDDED	CM8064601484501	S R181	929229
Intel® Core™ i7-4770TE Processor	I7-4770TE	C0	EMBEDDED	CM8064601538900	S R183	929231
Intel® Celeron® Processor G1820	G1820	C0	DESKTOP	CM8064601483405	S R1CN	930400
Intel® Xeon® Processor E3-1225 v3	E3-1225V3	C0	WORKSTATION	CM8064601466510	SR1KX	931054
Intel® Pentium® Processor G3420	G3420	C0	DESKTOP	CM8064601482522	S R1NB	931424
Intel® Core™ i3-4330 Processor	I3-4330	C0	DESKTOP	CM8064601482423	SR1NM	931586
Intel® Core™ i3-4350T Processor	I3-4350T	C0	DESKTOP	CM8064601481957	S R1PA	931888
Intel® Core™ i3-4360 Processor	I3-4360	C0	DESKTOP	CM8064601482461	S R1PC	931890
Intel® Core™ i7-4790S Processor	I7-4790S	C0	DESKTOP	CM8064601561014	SR1QM	931984
Intel® Core™ i5-4590S Processor	I5-4590S	C0	DESKTOP	CM8064601561214	SR1QN	931994
Intel® Core™ i5-4590T Processor	I5-4590T	C0	DESKTOP	CM8064601561826	S R1S6	932361
Intel® Core™ i3-4340TE Processor	I3-4340TE	C0	EMBEDDED	CM8064601618605	S R1T5	932855
Intel® Celeron® Processor G1820TE	G1820TE	C0	EMBEDDED	CM8064601618705	S R1T6	932857

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
May 29, 2020	00	Originally Published PCN
July 9, 2020	01	Corrected the list of affected products

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117615 - 01

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